

TECHNICAL VISIT TO “TM RESEARCH & DEVELOPMENT SDN BHD”

Organised by Engineering Education Technical Division (E2TD)

BEM Approved CPD/PDP hours: 2.0 Hours Ref. No.: IEM17/HQ/485/V

Date : 28TH MARCH 2018 (Wednesday)
Time : 2.00 P.M. to 4.30 P.M.
Venue : TM RESEARCH & DEVELOPMENT SDN BHD
TM Innovation Centre
Lingkar Teknokrat Timur
63000 Cyberjaya, Selangor Darul Ehsan
Transport: OWN TRANSPORTATION

Commitment fees inclusive of GST
(Non refundable & non transferable)

IEM Member : RM 50.00
Non Member : RM 80.00

**(STRICTLY REGISTRATION AND PAYMENT
VIA IEM ONLINE)**

SYNOPSIS ABOUT TM RESEARCH & DEVELOPMENT SDN BHD

TM R&D is a Malaysian government approved R&D company and the innovation hub for Telekom Malaysia (TM) group. Research & Development as a function has always had a strategic role in TM. TM R&D started as a division in the early 80's; and later incorporated as a company in 2001. TM R&D support TM's vision to make life and business easier for a better Malaysia. Today, TM R&D are positioned as the key enabler to drive TM's digital aspiration as it moves beyond connectivity into new value-added digital and smart services, covering customer experience, process optimisation and new business opportunities.

One of the first few things TM R&D embarked on was to develop TM's very own all digital workforce management system (SWIFT) for TM R&D field operations in 2013. TM R&D developed own slotting algorithm to send work orders to our field force on the fly. Today this platform allows all interactions with the field operation teams for real-time nationwide tracking and monitoring of order fulfilment, restoration, up to CPE inventory.

Understanding that WiFi channel congestion is a key pain point for our customers, TM R&D developed a WiFi Optimiser mobile app just for TM R&D UniFi customers. This tool allows customers to be in control of the quality of their WiFi signal by allowing them to measure signal quality; and change their WiFi channel without having to log into their router. In the past, this could only be done by TM R&D field force on site. This tool is available on Google Play Store and soon on Apple App Store just for TM R&D UniFi customers. In collaboration with TM R&D trusted partners in TM, this app won the Best Customer Care: Business Category at the ACA Awards held in June 2017 in Singapore.

TM R&D are making inroads in the IoT space with the establishment of an Integrated Smart Services Exchange Framework (iSSEF) adopted at Menara TMOne in Damansara to enable smarter business experience with smart security and smart parking currently in Beta at TMOne. On the connectivity front, TM R&D developed a universal copper analysis tool (U-CAST) to detect the root cause of a faulty copper cable and to estimate line speed without requiring power at the customer end; something TM R&D could not do before.

TM R&D has made significant contributions to the world standardisation bodies. TM R&D copper research findings have been adopted by the Broadband Forum under working group 285 Physical Layer Transmission this year while our proposal for Multiservice G.RoF System for Indoor DAS Applications have been accepted into the ITU-T SG15: Networks, Technologies and Infrastructures for Transport, Access and Home in 2016.



PROGRAMME:

TIME	ACTIVITIES
2:00pm-2.15pm	Arrival of Guest
2:15pm-2.45pm	Welcome and Briefing
2.45pm -3.45pm	Product Showcase and Lab Tour
3.45pm -4.00pm	Group Photo Session
4.00pm-4.30pm	Refreshment and Adjourn

- The visit is strictly limited to **30 participants** registered on a first-come, first-served basis.
- Interested participants are to register and pay online at www.myiem.org.my or register by returning the appended registration form **before 22 MARCH 2018** together with the payment.
- Cheques are to be made payable to **The Institution of Engineers, Malaysia.**
- Please note that the commitment fee must be settled prior to the visit.
- After this closing date, IEM reserves the right to allocate seats on first come first pay basis.
- Members are also reminded that IEM **MAY** cancel the reservation if payment is not received before the closing date

REPLY SLIP -

Fax: 03-7957 7678 / Email: shahrul@iem.org.my

I wish to participate in the above visit on **28 MARCH 2018**. I enclosed herewith a cheque No.....for the amount of RM..... as my commitment fee for the visit.

Name: Member No: Grade :
Company:..... Designation :.....
Contact Number :..... IC Number :.....
Email address : Company address

I will be participating in the visit at my own risk and hereby indemnify fully the IEM from all claims arising from any injury, damage or loss that may be sustained by me.

Ir. Assoc. Prof. Dr. Mandeep Singh
Chairman, Engineering Education Technical Division (E2TD), IEM